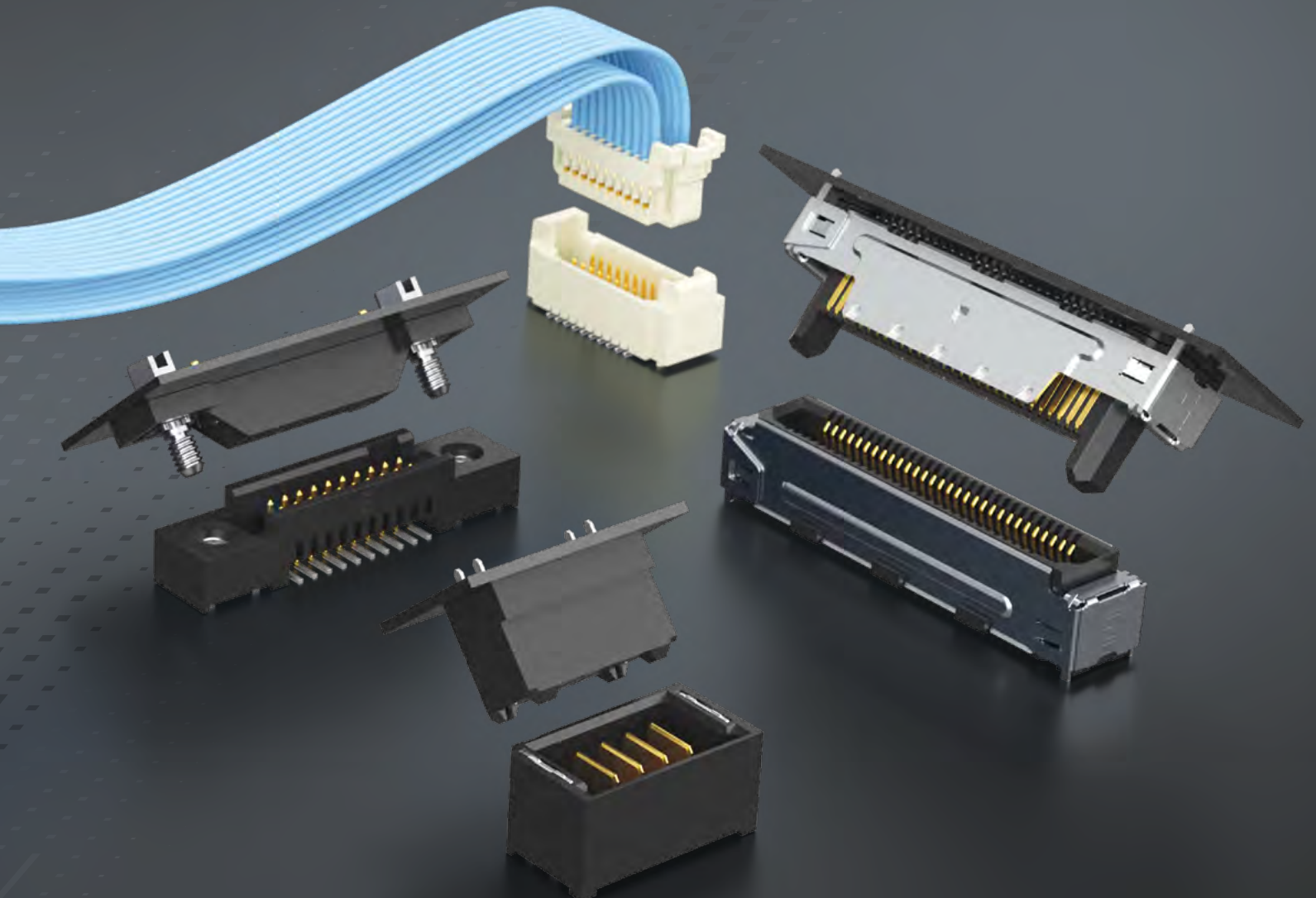




MICRO RUGGED

APPLICATION DESIGN GUIDE



MICRO RUGGED INTERCONNECT SOLUTIONS

Rugged contact systems, micro power interconnects and rugged signal integrity create the foundation of Samtec's micro rugged solutions for high cycle, high power and harsh environment applications. Samtec's rugged products are offered in conjunction with full engineering support, online tools and a service attitude that is unmatched in the connector industry.

MP

MICRO POWER

3 TO 30 AMPS

CONFIGURABILITY OF
POWER & SIGNAL

SPACE-SAVING FORM FACTOR



SI

RUGGED SIGNAL INTEGRITY

HIGH SPEEDS TO 40 Gbps

EDGE RATE® CONTACT DESIGN
INCREASES WEAR LIFE

EXPERTISE IN SIGNAL
INTEGRITY DESIGN & ANALYSIS



R

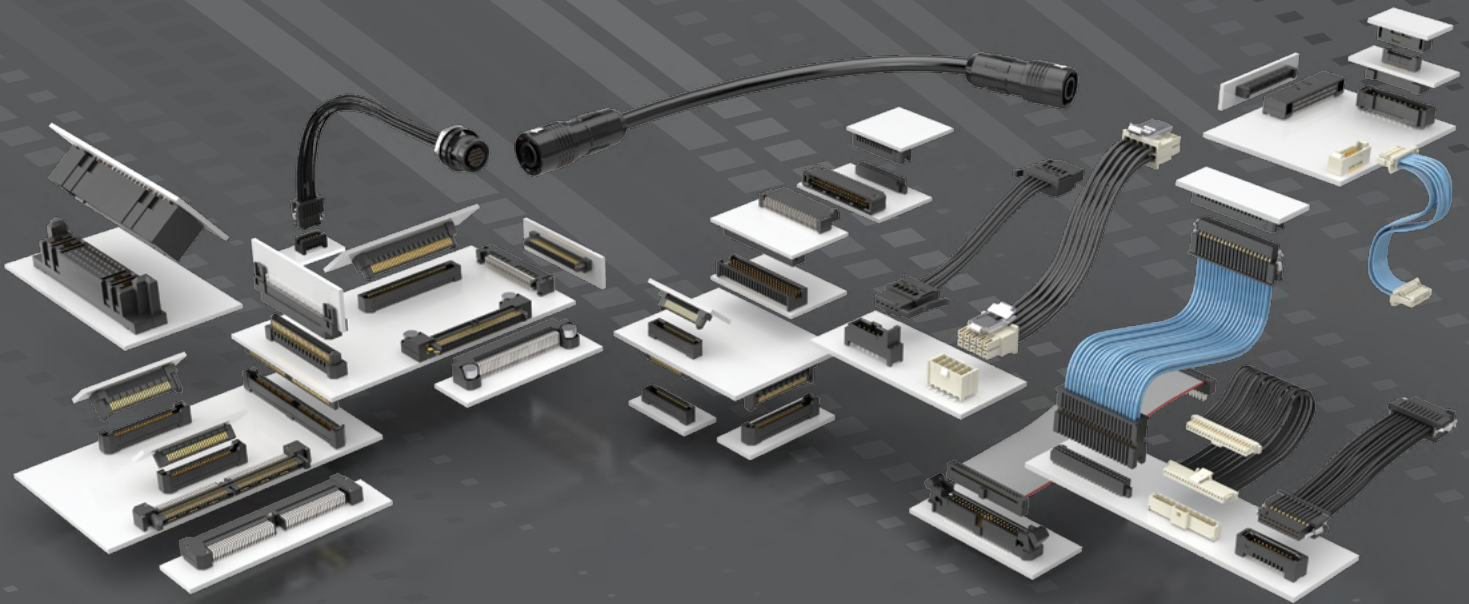
RUGGED CONTACT SYSTEM

1,000+ MATING CYCLES

TIGER EYE™ HEAT-TREATED BeCu CONTACTS

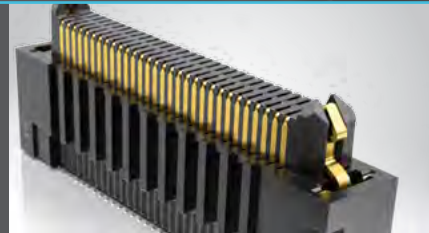
REDUNDANT POINTS OF CONTACT FOR HIGH-RELIABILITY

Learn more at
www.samtec.com



BOARD-TO-BOARD SYSTEMS

- Edge Rate® system for rugged signal integrity performance
- Tiger Eye™ contact system for high-reliability in rugged applications
- 0.50 mm to 2.00 mm pitch
- Stack heights from 5 mm to 18 mm



4-9

MICRO POWER SYSTEMS

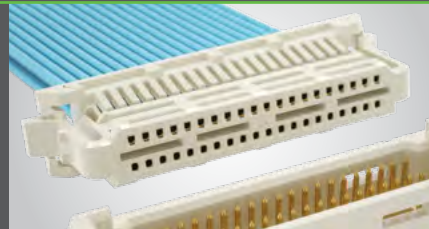
- 3 to 30 A per power blade
- Small form factor
- Micro power/signal combinations
- Variety of pitches



10-11

DISCRETE WIRE ASSEMBLIES

- Choice of pitch as low as 0.80 mm
- Rugged, high-performance Tiger Eye™ systems
- Individually shrouded contacts
- High power systems to 34.5 A per power blade



12-13

SEALED I/O SYSTEMS

- IP68 and IP67 rated for dust and water
- Variety of circular shell sizes with power, power/signal pin outs
- Rectangular designs for space savings
- Rugged latching



14

Modified & Custom Solutions

15

Solutionator®

16

Rugged Features

17

Power Integrity & Extended Life Product™

18

Full System Signal Integrity

19

SI R MP

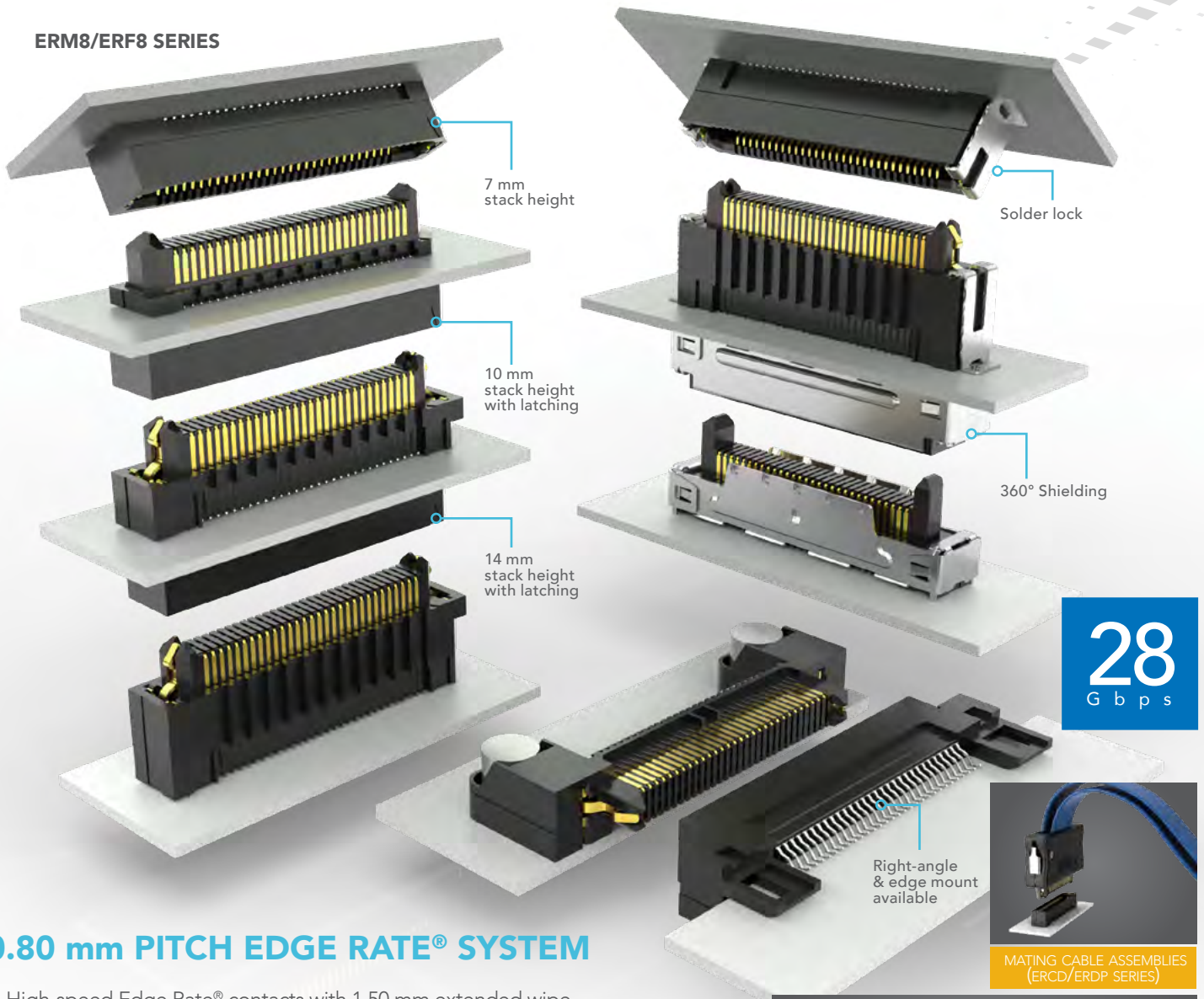
EDGE
RATE
CONTACT



EDGE RATE[®] CONTACT SYSTEMS

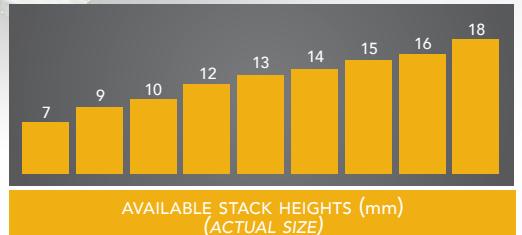
OPTIMIZED FOR SI PERFORMANCE • INCREASED CONTACT WIPE • HIGH CYCLES

ERM8/ERF8 SERIES



0.80 mm PITCH EDGE RATE[®] SYSTEM

- High-speed Edge Rate[®] contacts with 1.50 mm extended wipe
- Rugged metal latching for increased retention force
- 360° shielding option reduces EMI
- Cost-effective metal solder lock in development for a more secure connection to the board



? Samtec designs and builds all automation equipment in-house.

MICRO POWER SYSTEM

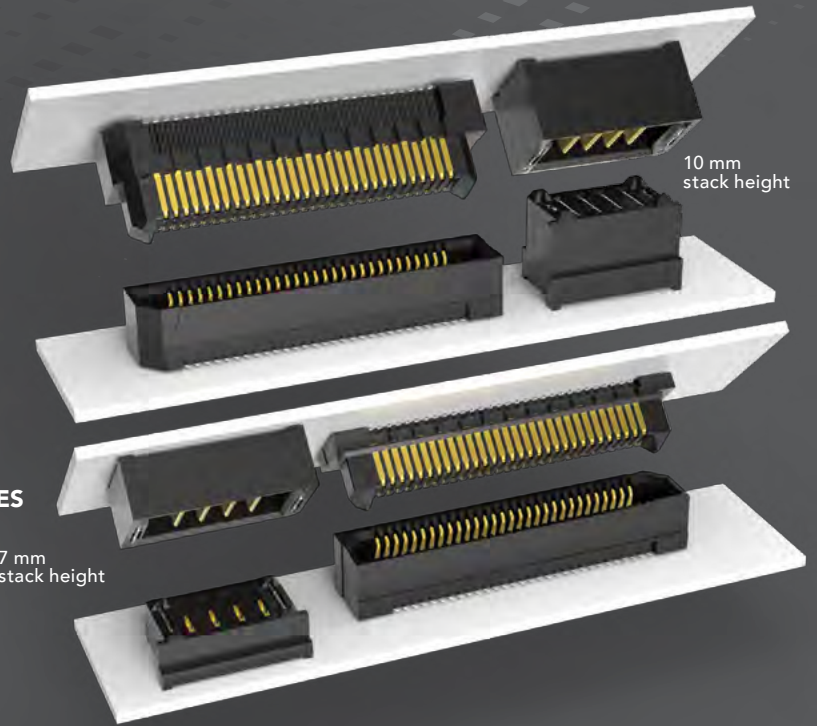
- Use with Samtec's Edge Rate® and other high-speed systems for power/signal applications
- 5 mm to 20 mm stack heights
- 2 to 5 power blades on a 2.00 mm pitch
- Allows for staging of power and signal/ground
- Modular interlocking, shielding and right-angle options in development



2.00 mm PITCH VS.
3.81 mm PITCH (UPX SERIES)

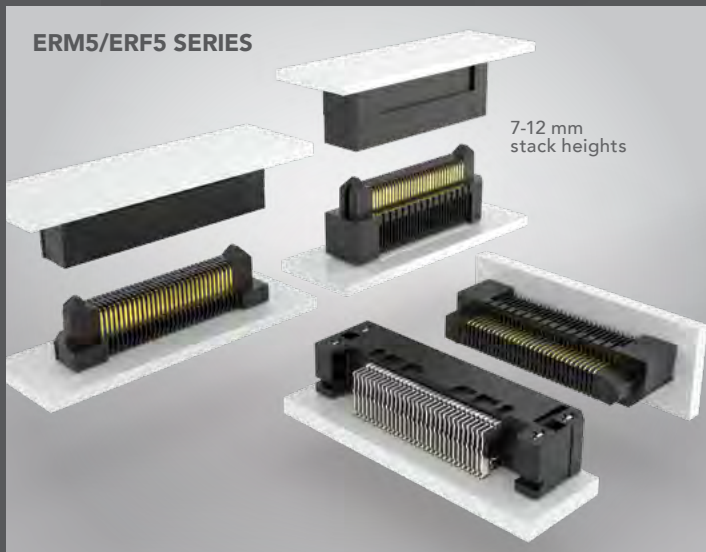
UMPT/UMPS SERIES

15 A
per power pin
4 pins powered



0.50 mm PITCH EDGE RATE®

- 1.00 mm contact wipe for a reliable connection
- 28 Gbps high-speed channel performance*
- Rugged friction locks and weld tabs available
- Up to 40% PCB space savings vs. ERM8/ERF8

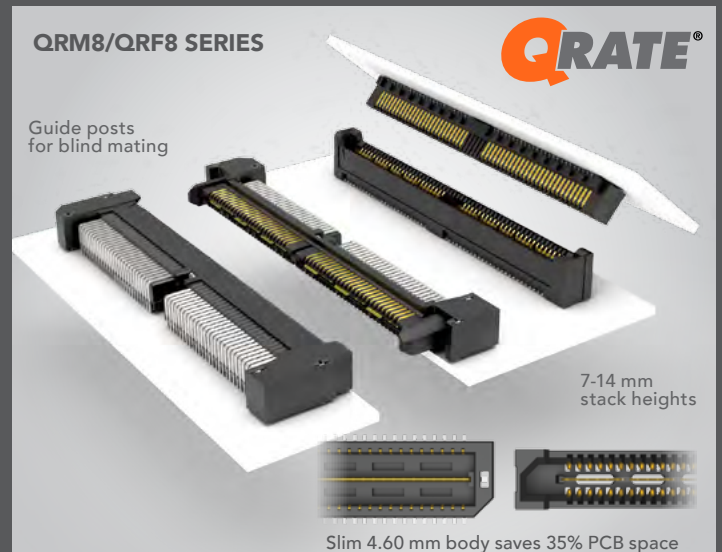


ERM5/ERF5 SERIES

7-12 mm
stack heights

Q RATE® SLIM GROUND PLANE

- Widely accepted industry standard integral power/ground plane
- 0.80 mm pitch with 1.20 mm contact wipe
- 31 Gbps high-speed channel performance*



QRM8/QRF8 SERIES

Guide posts
for blind mating



7-14 mm
stack heights

Slim 4.60 mm body saves 35% PCB space

* High-speed channel performance figure based on Samtec reference channel. For full SI Performance data visit samtec.com or contact sig@samtec.com

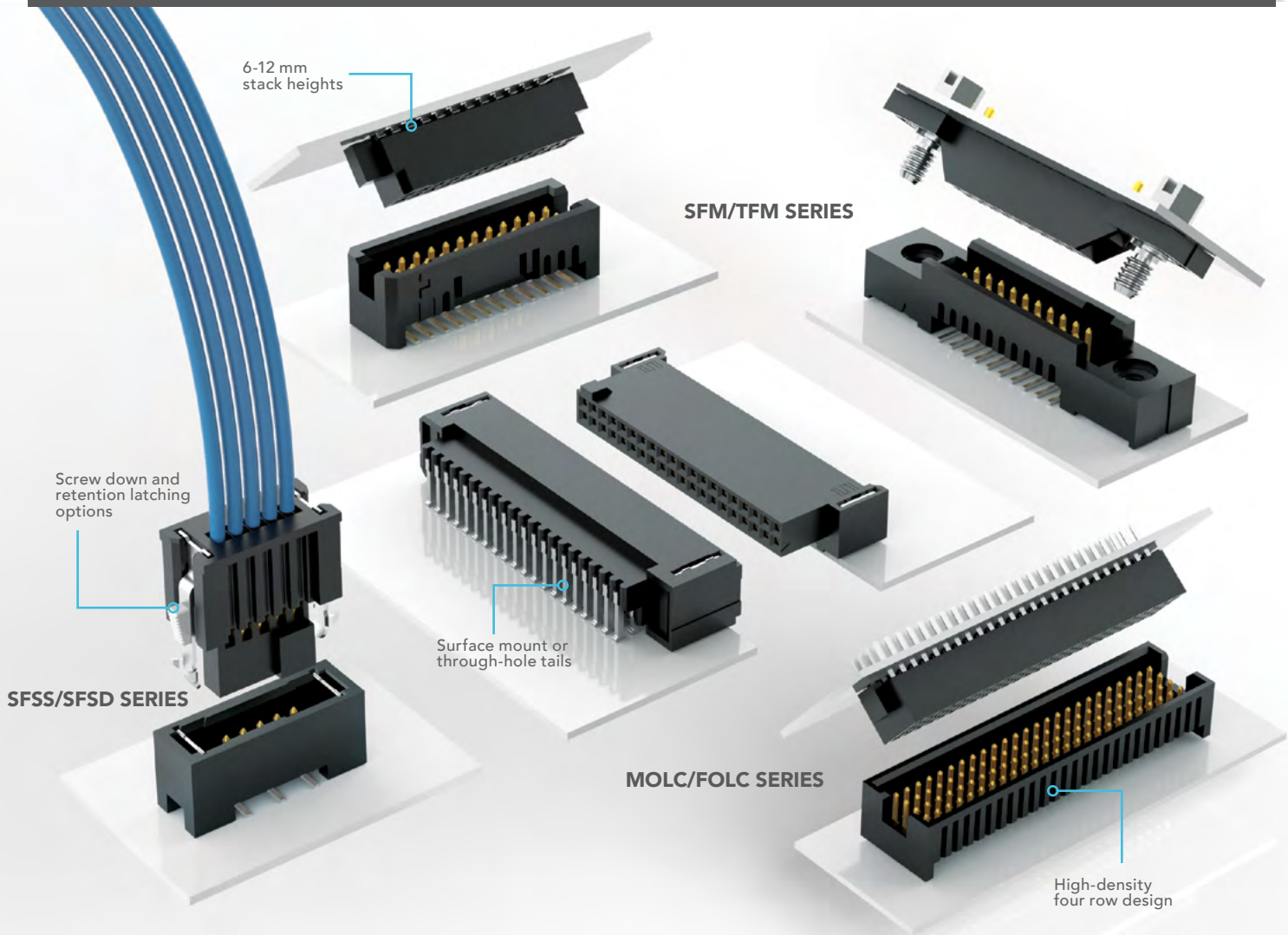
R MP

TIGER EYE™ CONTACT SYSTEMS

TIGER EYE™ CONTACT



HIGH-RELIABILITY • MULTI-FINGER BeCu CONTACT • HIGH MATING CYCLES



6-12 mm stack heights

SFM/TFM SERIES

Screw down and retention latching options

SFSS/SFSD SERIES

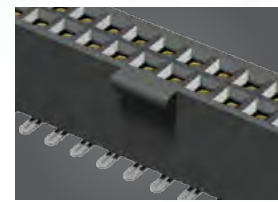
Surface mount or through-hole tails

MOLC/FOLC SERIES

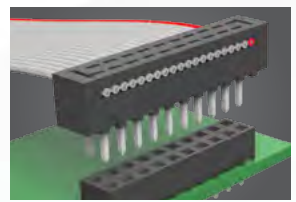
High-density four row design

1.27 mm PITCH TIGER EYE™ SYSTEM

- Tiger Eye™ is Samtec's most rugged contact system rated to 1,000+ mating cycles
- Screw down, locking clip, friction latching and weld tab ruggedizing options
- Shrouded, polarized and keyed
- Discrete wire assemblies available in single or double row, 30 and 28 AWG PVC or Teflon® wire



LOCKING FOR INCREASED UNMATING FORCE (SFML SERIES)



MATING IDC CABLE ASSEMBLIES (FFXD & FFXP SERIES)

Dupont™ Teflon® is a registered trademark of the E.I. du Pont de Nemours and Company or its affiliates.

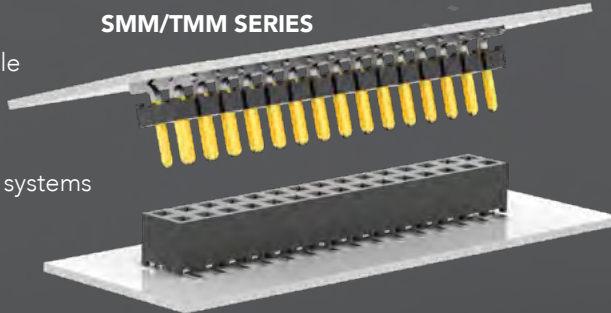


Samtec stamps over
1 BILLION Tiger Eye™
contacts per year.

2.00 mm PITCH TIGER EYE™ SYSTEM

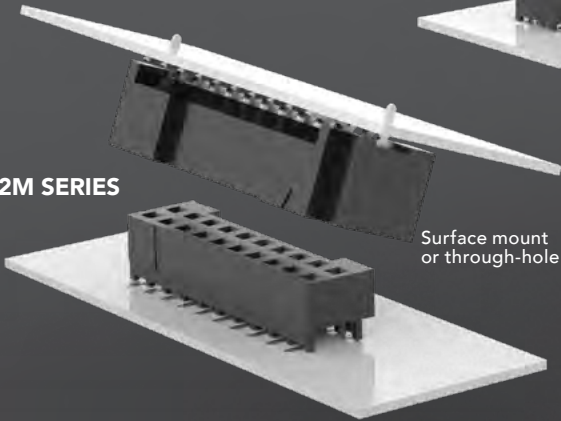
- Wide range of stack heights
- Right-angle mating headers available
- Optional screw downs, weld tabs and locking clips
- Mating discrete wire and IDC cable systems

SMM/TMM SERIES



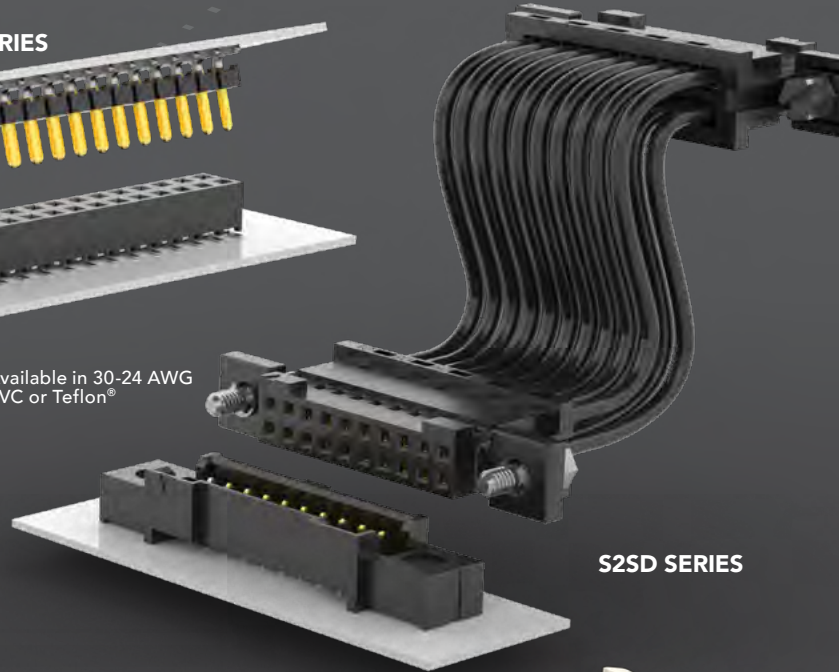
Available in 30-24 AWG
PVC or Teflon®

S2M/T2M SERIES



Surface mount
or through-hole

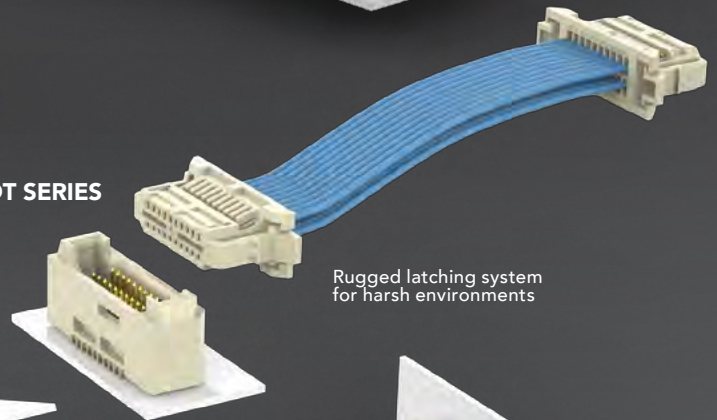
S2SD SERIES



0.80 mm PITCH TIGER EYE™ SYSTEM

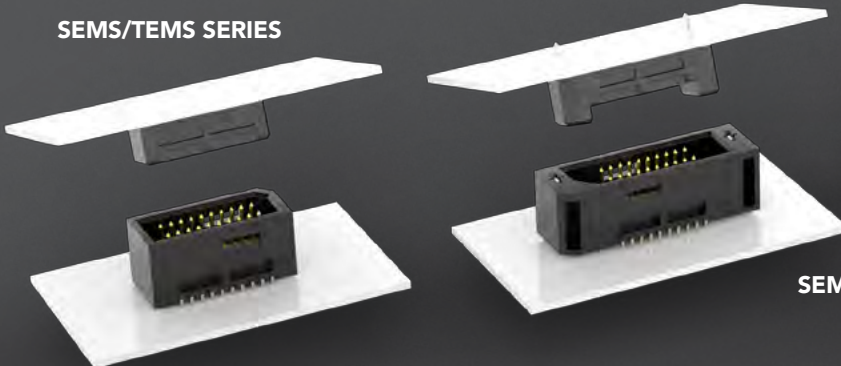
- Micro pitch and slim body for space-savings
- 6 mm, 7 mm and 10 mm stack heights
- Locking clip, alignment pins and weld tab ruggedizing features
- Discrete wire assembly with 32 AWG Teflon® wire

SESDT SERIES

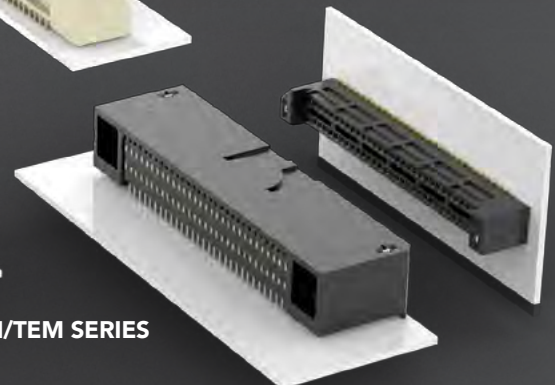


Rugged latching system
for harsh environments

SEMS/TEMS SERIES



SEM/TEM SERIES



Vertical and right-angle
mating headers

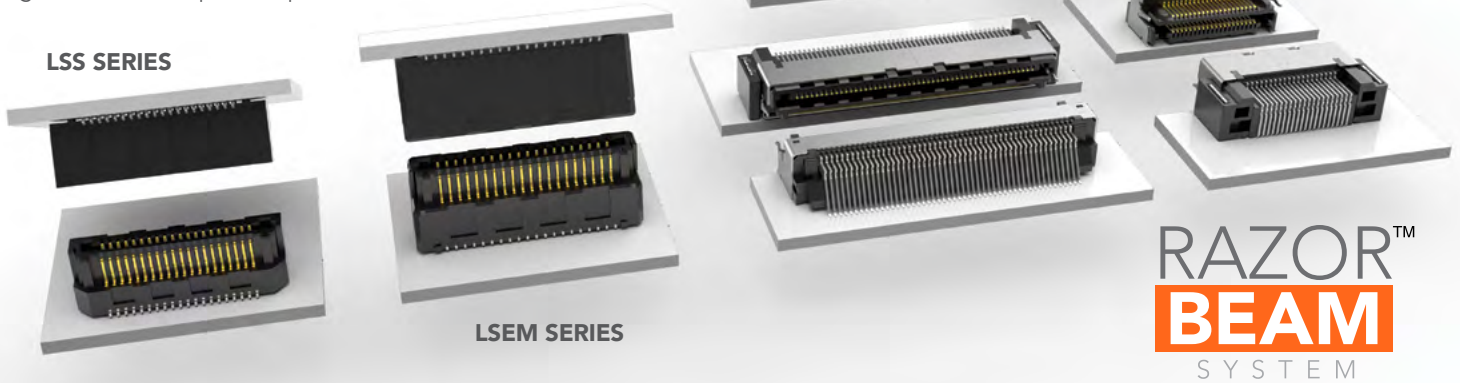
MICRO SYSTEMS

HIGH-DENSITY • HIGH-RETENTION CONTACTS • SLIM ROW-TO-ROW DESIGNS

HERMAPHRODITIC RAZOR BEAM™ INTERFACES

- High-retention, high-speed Razor Beam™ contacts
- 26 Gbps high-speed channel performance*
- 0.50 mm, 0.635 mm and 0.80 mm pitch
- EMI shielding available to limit signal degradation and optimize performance

5 - 12 mm stack height flexibility



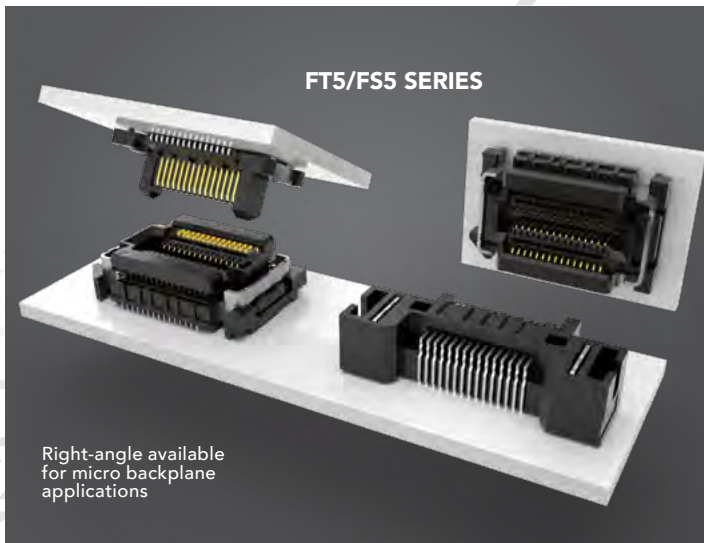
RAZOR BEAM™
SYSTEM

FLOATING CONNECTORS

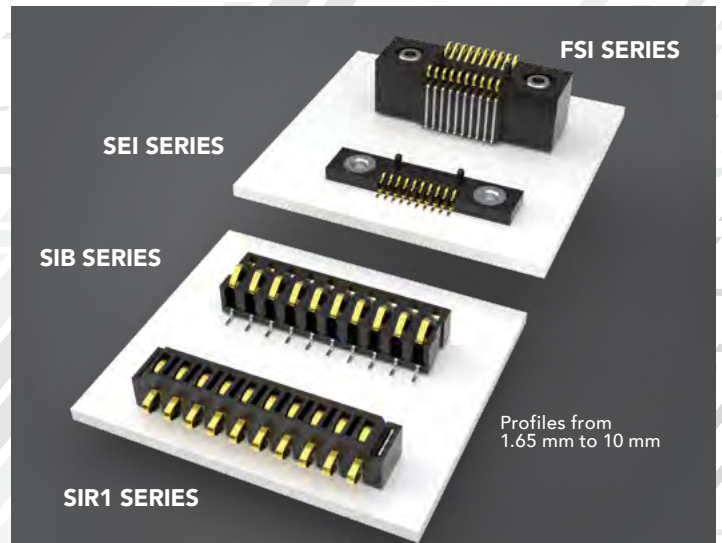
- Provides 0.50 mm contact float in the X and Y axes to compensate for misalignment
- 5 mm and 7 mm stack heights
- Micro 0.50 mm pitch

ONE-PIECE INTERFACES

- Robust design and mechanical hold-downs for high-shock and vibration applications
- Optional rugged weld tabs and locking clips
- 1.00 mm, 1.27 mm and 2.54 mm pitch designs



Right-angle available for micro backplane applications



Profiles from 1.65 mm to 10 mm

* High-speed channel performance figure based on Samtec reference channel. For full SI Performance data visit samtec.com or contact sig@samtec.com

SI R MP

HIGH-SPEED EDGE CARD

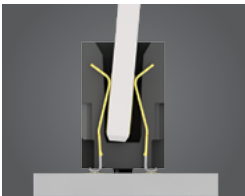
? Lead times for custom products are often the same as for Samtec's standard products.

16 TO 40 Gbps • CHOICE OF PITCH • EDGE RATE® CONTACTS

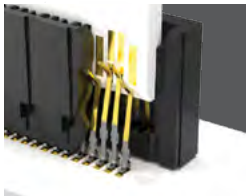
0.80 mm & 1.00 mm PITCH SYSTEMS

- High-speed Edge Rate® contact system
- Vertical, right-angle and edge mount
- Power/signal combo to 60 A per power bank
- Pass-through application

HSEC8 SERIES



MISALIGNMENT MITIGATION (HSEC1-DV SERIES)



40 Gbps WITH DIFFERENTIAL PAIR (HSEC8-DP SERIES)



40 Gbps

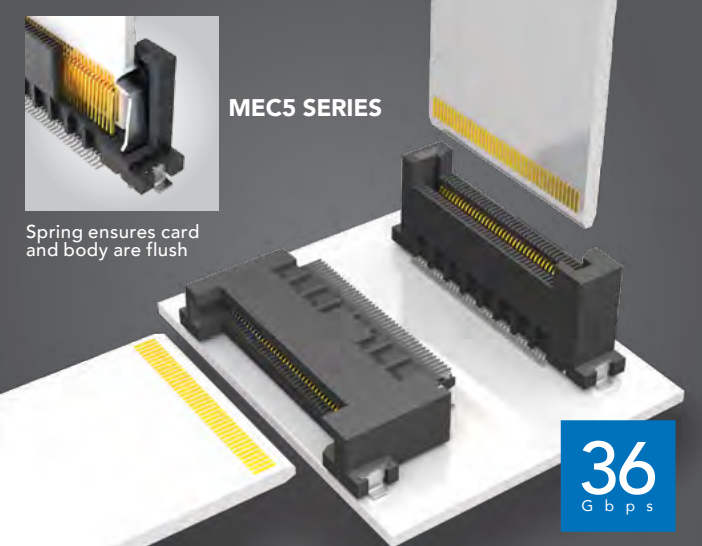
Rugged locking, latching and weld tab options

HSEC8-PV SERIES

HSEC1-DV SERIES

HIGH-DENSITY EDGE CARD SYSTEM

- Justification beam enables use of standard PCB tolerance
- 0.50 mm ultra-fine pitch with up to 200 total I/Os
- PCIe® Gen 4 compliant



MEC5 SERIES

Spring ensures card and body are flush

36 Gbps

MICRO EDGE CARD SYSTEMS

- 0.635 mm, 0.80 mm, 1.00 mm, 1.27 mm and 2.00 mm pitch
- Optional rugged weld tabs, board locks and solder locks
- Solutions for 1.60 mm (0.62") and 2.36 mm (.093") thick cards



MECF SERIES

MEC6 SERIES

24 Gbps

MEC8 SERIES

PCI-SIG®, PCI Express® and the PCIe® design marks are registered trademarks and/or service marks of PCI-SIG.

POWER/SIGNAL SYSTEMS

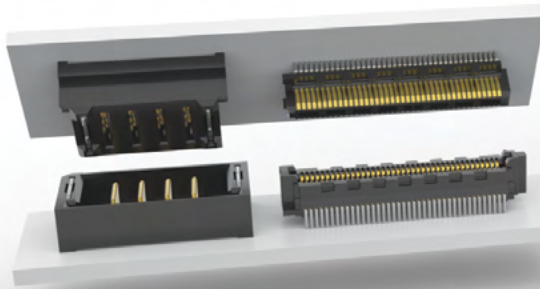
3 TO 15 A PER BLADE • MICRO PITCH • DESIGN FLEXIBILITY AND CONFIGURABILITY

MICRO POWER SYSTEMS

- 5 mm to 20 mm stack heights
- Use with Samtec's high-speed connector systems
- Design flexibility as a two-piece system for power/signal applications
- 2 to 5 power blades on a 2.00 mm pitch

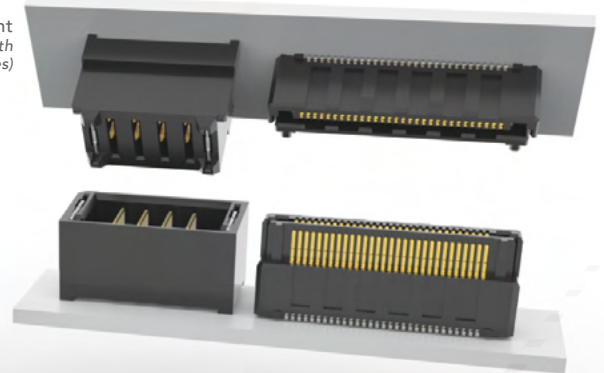


2.00 mm PITCH VS.
3.81 mm PITCH (UPX SERIES)



10 mm stack height
Micro Power shown with
Razor Beam™ (LSHM Series)

UMPT/UMPS SERIES

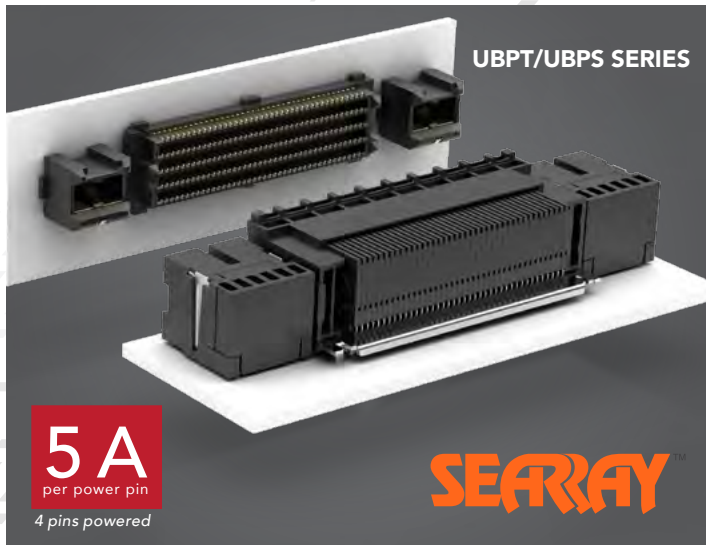


5 mm stack height
Micro Power shown with
Razor Beam™ LP (ST4/SS4 Series)

15 A
per power pin
4 pins powered

SEARAY™ HIGH-DENSITY POWER/SIGNAL COMBO

- Vertical and right-angle power modules for use with SEARAY™ and SEARAY™ 0.80 mm
- 0.80 mm and 1.27 mm pitch open-pin-field arrays
- Edge Rate® contact system less prone to damage when "zippered" to unmate



UBPT/UBPS SERIES

5 A
per power pin
4 pins powered

SEARAY™

Q2™ POWER/SIGNAL COMBO

- Increased insertion depth for rugged applications
- 0.635 mm pitch with integral power/ground plane
- Shielding, power pins, retention pins and RF options
- Eight total power pins at 4 A per pin (4 pins powered)



QMSS/QFSS SERIES

15 A
ground plane

Q2™



Custom designs make up almost 28% of Samtec's business. See page 15 for more information.

R MP

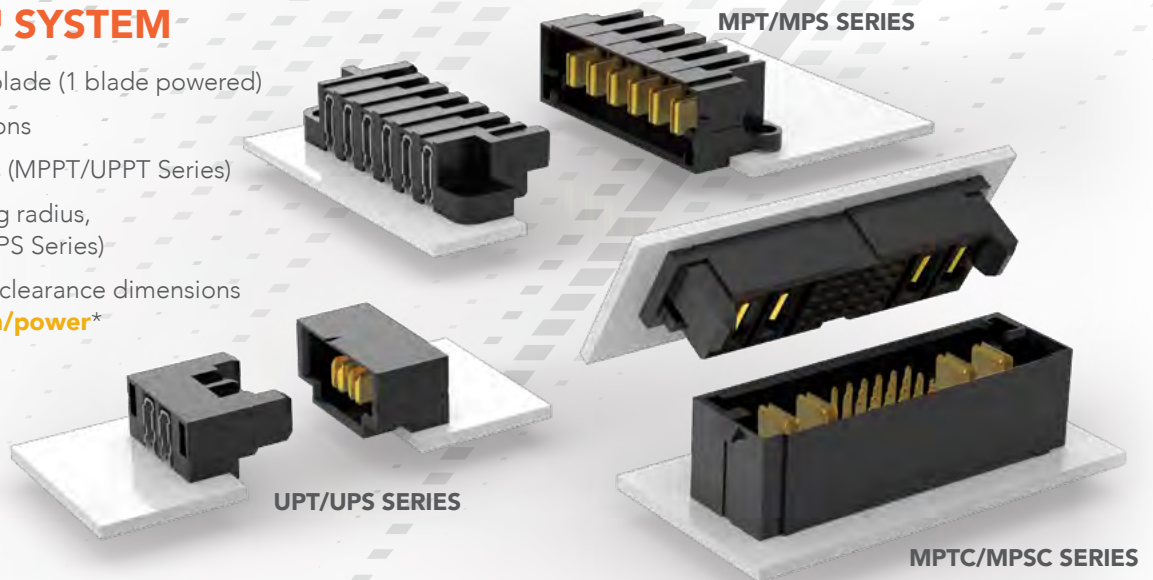
HIGH POWER SYSTEMS

20 TO 60 A PER BLADE • CHOICE OF PITCH • LOW PROFILE DESIGNS

POWERSTRIP™ SYSTEM

- 23.5 A/blade to 58.7 A/blade (1 blade powered)
- Power/signal combinations
- Hermaphroditic headers (MPPT/UPPT Series)
- “Hinging” for 90° mating radius, blind mating (FMPT/FMPS Series)
- Standard creepage and clearance dimensions available at samtec.com/power*

POWERSTRIP™

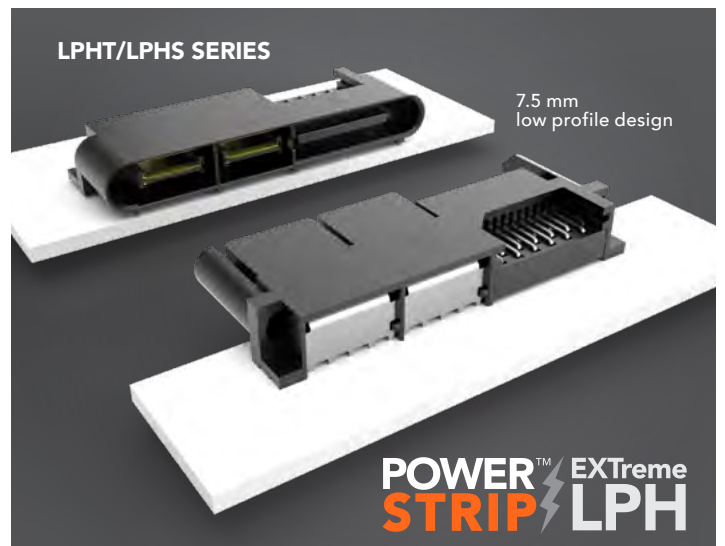
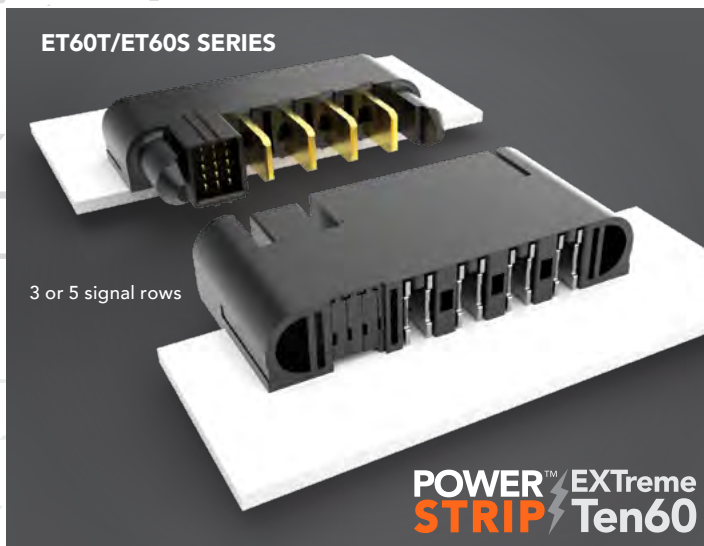


EXTREME TEN60POWER™

- Up to 60 A/blade (2 blades powered)
- High-density signals available in the same form factor
- AC power, AC-DC combos and split power options
- Standard creepage and clearance dimensions available at samtec.com/power*

EXTREME LPHPOWER™

- Up to 30 A/blade (4 blades powered)
- High-density, double stacked power blades
- 16, 20, 24 and 32 signal options
- Standard creepage and clearance dimensions available at samtec.com/power*



* For flexible design solutions to fit specific applications, contact Samtec.

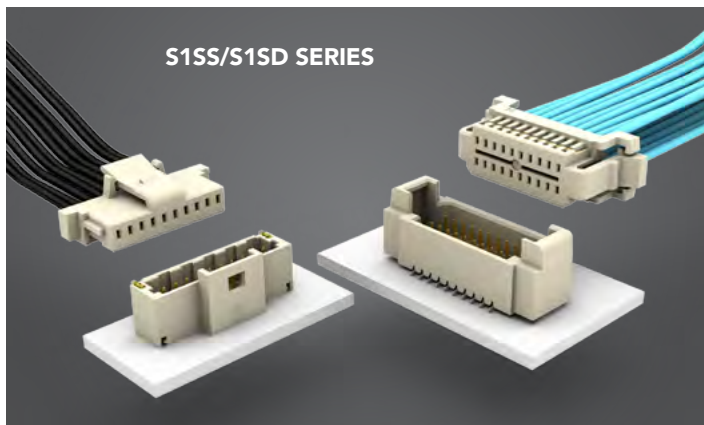


MICRO DISCRETE WIRE

CHOICE OF PITCH • 3 TO 35 A PER CONTACT • RUGGED LATCHING

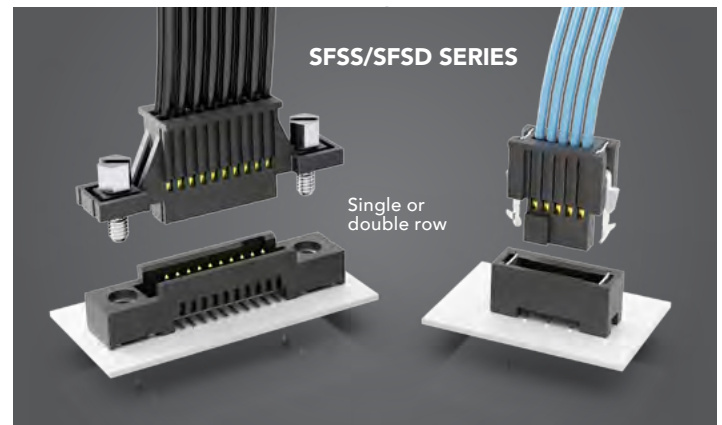
1.00 mm PITCH SYSTEM

- 3.3 A/contact*
- 2 to 20 total pins, single or double row
- Low profile down to 3.2 mm
- Available with or without retention latch



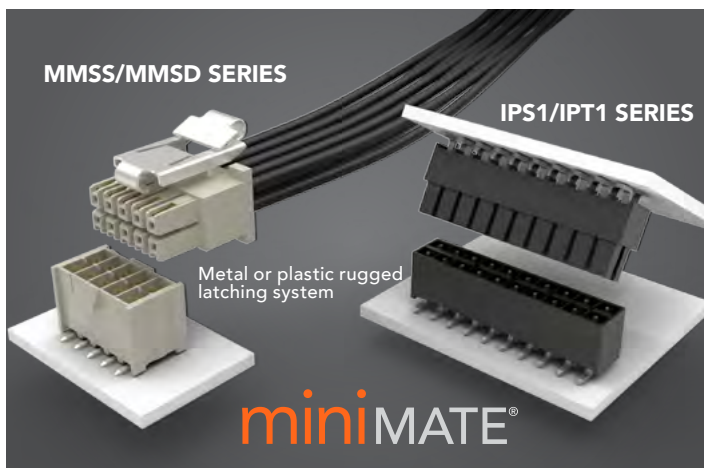
1.27 mm PITCH TIGER EYE™ SYSTEM

- 2.9 A/contact*
- High-reliability, multi-finger BeCu Tiger Eye™ contacts
- Rugged screw down and retention latch options



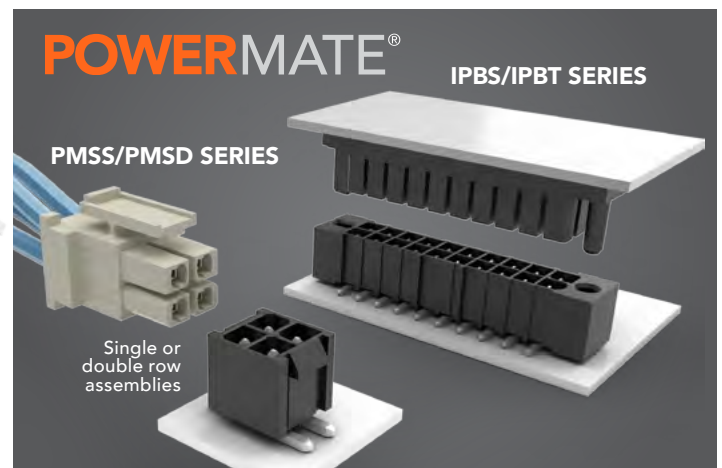
MINI MATE® SYSTEM

- 5.4 A/contact*
- .100" (2.54 mm) pitch with individually shrouded contacts
- Panel mount cable assembly accommodates panel thickness of 0.84 mm to 2.28 mm



POWER MATE® SYSTEM

- 10.3 A/contact*
- .165" (4.19 mm) pitch with individually shrouded contacts
- Standard creepage and clearance dimensions available at samtec.com/power**



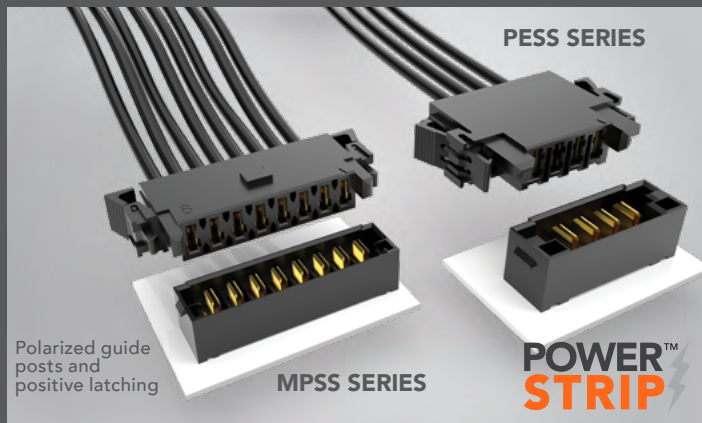
* 1 contact/blade powered per row ** For flexible design solutions to fit specific applications, contact Samtec.



36% of Samtec's discrete wire sales are modified and custom products. See page 15 for more information.

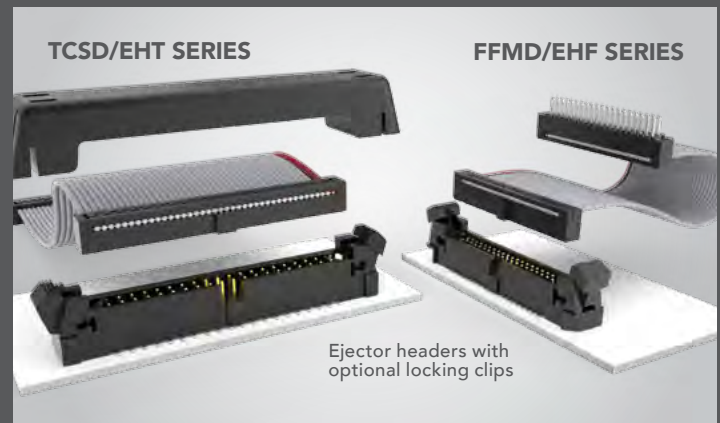
POWERSTRIP™ SYSTEM

- 5.00 mm pitch for performance to 23.2 A/blade* and 6.35 mm pitch for 34.5 A/blade* performance
- Power/signal combination
- Standard creepage and clearance dimensions available at samtec.com/power**



MICRO RUGGED IDC CABLE SYSTEMS

- 1.27 mm and 2.00 mm pitch systems with low 5.08 mm profile
- High-reliability Tiger Eye™ contacts
- Variety of options including rugged strain relief, polarization and daisy chains



DISCRETE WIRE COMPONENTS

- A broad selection of housings and contacts for build-it-yourself design and application flexibility
- Rugged screw downs, plastic and metal latches
- 32 to 10 AWG wire



DISCRETE WIRE TOOLING

- Hand tools and quick-change semi-automatic crimp applicators available
- Wide variety of additional application specific hardware and field service capabilities
- Visit samtec.com/discretewire or samtec.com/tooling



* 1 contact/blade powered per row ** For flexible design solutions to fit specific applications, contact Samtec.



ACCLIMATE™ SEALED I/O

IP67 & IP68 • BAYONET/PUSH-PULL CIRCULARS • SPACE-SAVING RECTANGULARS

FLEXIBLE SEALED CIRCULAR SYSTEMS

- Metal or plastic, 12 mm, 16 mm & 22 mm shells
- Flexible pin configuration, gender and panel interface termination
- Bayonet-style latching systems meet IP68 requirements
- Cost-effective crimp version available
- Mini push-pull latching system meets IP67 requirements for dust and waterproof sealing

ACP/ACR SERIES

16 mm size metal shell

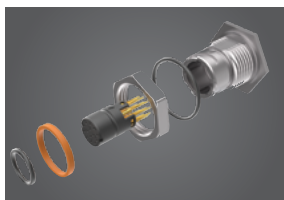


CCP/CCR SERIES

Crimp 12 mm shell

MCP/MCR SERIES

Mini push-pull system



KITTED COMPONENTS FOR
EFFICIENT FIELD ASSEMBLY

ACCLIMATE™

ETHERNET AND USB SEALED SYSTEMS

- IP68 threaded circulars with rugged overmold design
- Space-saving rectangulars with positive latching for quick connect/disconnect
- IP67 sealed USB Type C port seals to panel without costly metal screws or dust caps

RCE/RPBE SERIES

SCRUS/SCPU SERIES

SSU-C SERIES

Meets USB 2.0 and
base 3.1 standards

USB or Ethernet (meets
CAT3, CAT5 & CAT5e)

10 or 17 mm shell
size for Ethernet,
Mini USB and USB

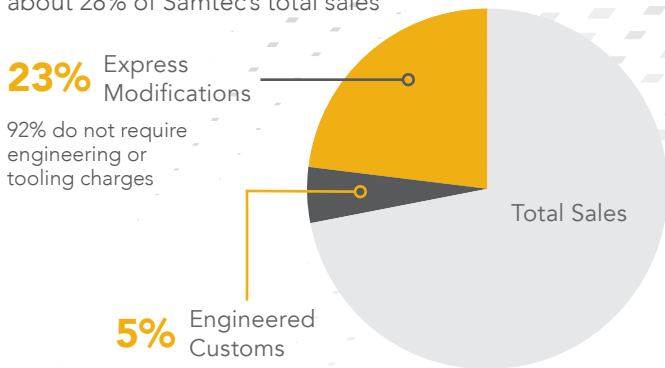


25-45% PANEL AREA SAVINGS

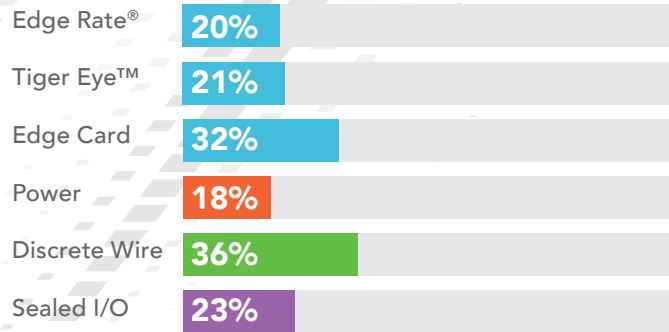
MODIFIED & CUSTOM SOLUTIONS

WILLINGNESS, SUPPORT & EXPERTISE

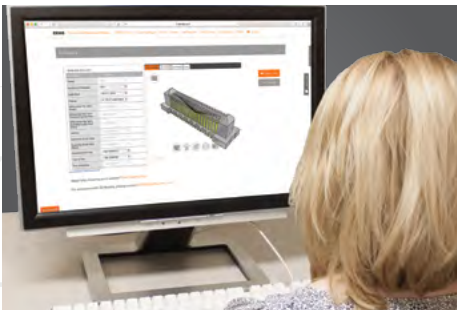
Customs and Modifications make up about 28% of Samtec's total sales



A substantial percentage of each Micro Rugged product segment is custom



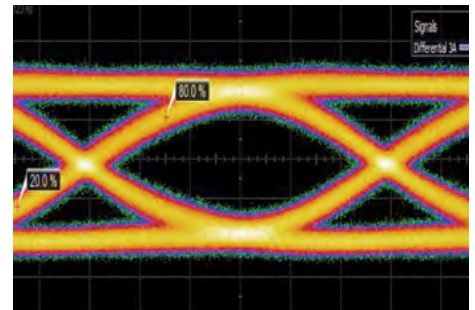
INDUSTRY LEADING CUSTOMER SERVICE



FLEXIBLE IN-HOUSE MANUFACTURING

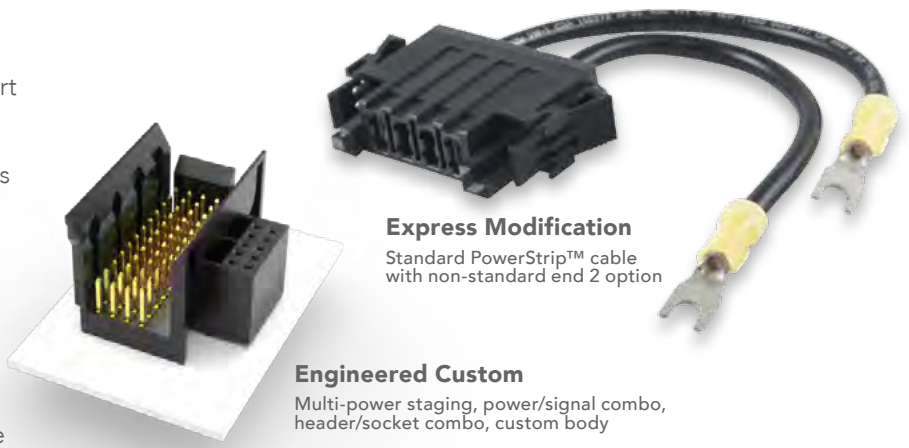


SIGNAL INTEGRITY EXPERTISE



FLEXIBLE CAPABILITIES

- Full engineering, design and prototype support
- Design, simulation and processing assistance
- Quotes and samples turned around in 24 hours
- Flexible, quick-turn manufacturing
- Dedicated Application Specific Product engineers and technicians
- Modified or custom options for board level connectors and cable assemblies including: contacts, bodies, stamping, plating, wiring, molding, ruggedizing features and much more



Contact the Application Specific Products Group at asp@samtec.com for express modifications or customasp@samtec.com for engineered customs.

SOLUTIONATOR®

QUICKLY BUILD MATED SETS ONLINE

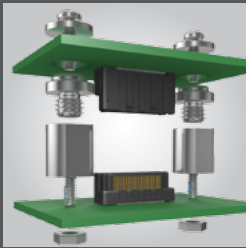
- Wide variety of search parameters and filters: creepage and clearance, pitch, stack height, etc.
- Easily sort results to find the right mated set
- Live chat with engineers for custom options
- Immediately download models and open Specs Kit

The screenshot displays the Solutionator website interface. At the top, there's a search bar and a 'Search Options' section with various filters. A callout box highlights the 'Pitch' filter set to '0.80 mm (.0315")' and the 'Stack Height' filter set to a range of '0' to '12' mm. Another callout box shows the 'Creepage' and 'Clearance' filters. Below the filters, there's an 'Active Filters' section showing the current search criteria. The main content area displays a table of 87 results. A callout box at the top right shows the '3D/2D CAD or graphic file' download options for two specific part numbers: ERM8-030-02.0-L-DV-TR and ERF8-030-07.0-S-DV-TR. A 'Live Chat' button is visible on the right side of the interface.

Part Number	Mating Part Number	Pitch	Mated Stack Height (mm)	Positions	Board Termination	Mating Orientation	Rugged Rating	Signal Integrity Rating	Creepage (mm)
ERM8-030-02.0-L-DV-TR	ERF8-030-07.0-S-DV-TR	0.80 mm (.0315")	9	60	Surface Mount	Parallel	3 - Edge Rate	NA	NA
ERM8-070-02.0-L-DV-TR	ERF8-070-07.0-S-DV-TR	0.80 mm (.0315")	9	140	Surface Mount	Parallel	3 - Edge Rate	NA	NA
ERM8-050-05.0-L-DV-K-TR	ERF8-050-05.0-L-DV-K-TR	0.80 mm (.0315")	10	100	Surface Mount	Parallel	3 - Edge Rate	16 GHZ	NA
ERM8-070-02.0-L-DV-TR	ERF8-070-05.0-L-DV-TR	0.80 mm (.0315")	7	140	Surface Mount	Parallel	3 - Edge Rate	12 GHZ	NA
ERM8-052-05.0-L-D-A	ERF8-052-07.0-L-D-A	0.80 mm (.0315")	12	104	Surface Mount	Parallel	3 - Edge Rate	NA	NA
ERM8-020-05.0-L-DV-TR	ERF8-020-07.0-L-DV-TR	0.80 mm (.0315")	12	40	Surface Mount	Parallel	3 - Edge Rate	NA	NA
SEAM8-10-S02.0-S-10-2-K	SEAF8-10-05.0-S-10-2-K	0.80 mm (.0315")	7	100	Surface Mount	Parallel	3 - Edge Rate	12 GHZ	NA
FRM8-025-02.0-L-DV-TR	FRF8-025-05.0-S-DV-TR	0.80 mm (.0315")	7	50	Surface Mount	Parallel	3 - Edge Rate	12 GHZ	NA
ERM8-010-02.0-L-DV-TR	ERF8-010-05.0-S-DV-TR	0.80 mm (.0315")	7	20	Surface Mount	Parallel	3 - Edge Rate	12 GHZ	NA
ERM8-070-05.0-L-DV-TR	ERF8-070-05.0-L-DV-TR	0.80 mm (.0315")	10	140	Surface Mount	Parallel	3 - Edge Rate	16 GHZ	NA
ERM8-025-02.0-L-DV-K-TR	ERF8-025-05.0-L-DV-K-TR	0.80 mm (.0315")	7	50	Surface Mount	Parallel	3 - Edge Rate	12 GHZ	NA

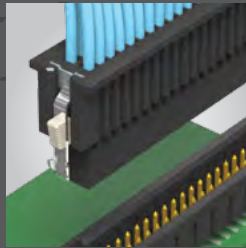
RUGGED FEATURES

RUGGEDIZING OPTIONS



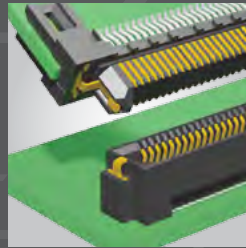
JACK SCREWS

Ideal for high normal force, zipping and other rugged applications



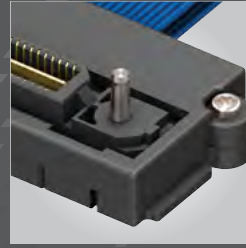
POSITIVE LATCHING

Manually activated latches increase unmating force by up to 200%



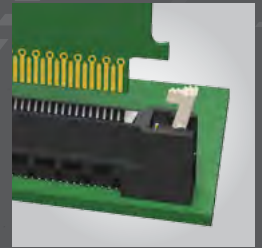
FRICTION LOCKS

Metal or plastic friction locks increase retention/withdrawal force



RETENTION PINS

Increase unmating force by up to 50%



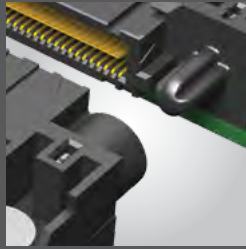
BOARD LOCKS

Boards are mechanically locked together



WELD TABS

Significantly increase shear resistance of connector to PCB



GUIDE POSTS

Easy and secure mating



SHIELDING

360° shielding reduces EMI



SCREW DOWNS

Secure mechanical attachment to the board



BOARD STANDOFFS

Precision machined standoffs for 5 mm to 25 mm board spacing

CONTACT SYSTEMS



TIGER EYE™

High-reliability
High Mating Cycles
Multi-finger Contact



TIGER CLAW™

Dual Wipe Contact
Pass-through Applications
Ultra-low Profile



BLADE & BEAM

Mating/Alignment "Friendly"
Cost-effective



TIGER BEAM™

Best Cost
Reliable Performance
Post & Beam Contact



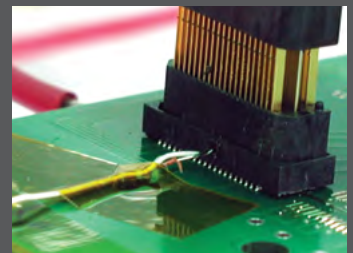
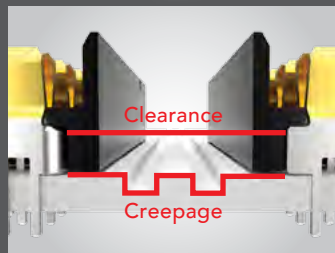
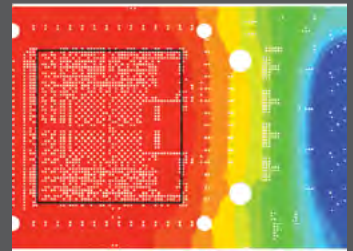
EDGE RATE®

Designed for Signal Integrity
Superior Impedance Control
Reduced Broadside Coupling

POWER INTEGRITY & E.L.P.TM

POWER INTEGRITY SERVICES

- Standard power test data, including current carrying capacity, working voltage, voltage drop and resistance, creepage and clearance, is available for select power systems
- Current Cycling Test Data, which demonstrates connector performance in realistic and common applications, is available for select series
- Power Integrity Guidelines are based on test data and proven design parameters, and are designed to help in connector selection and PCB design maximization
- Power Integrity Certified products undergo testing and additional requirements unique to Samtec. To be certified, products must pass Current Cycling Test EIA 365-55, have current carrying capacity, resistance and amps vs. number of contacts data available and Power Integrity Guidelines developed
- Visit samtec.com/powerintegrity for more information



EXTENDED LIFE PRODUCTTM

E.L.P.TM products are tested to rigorous standards, which evaluate contact resistance in simulated storage and field conditions.



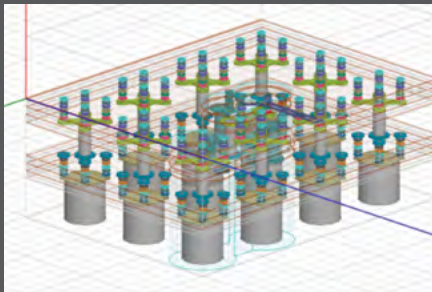
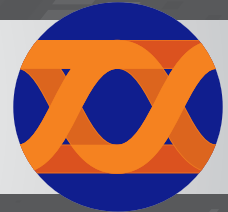
- 10 year Mixed Flowing Gas (MFG)
- High Mating Cycles (250 to 2,500)
- Certain plating and/or contact options will apply
- For complete details on Samtec's E.L.P.TM program, a list of qualifying products and test results, please visit samtec.com/ELP or email the Customer Engineering Support Group at CES@samtec.com

PITCH	TYPE	CONTACT	SERIES*
0.50 mm	Q Series [®] Strip	Blade & Beam	QSH/QTH
	Basic Strip	Blade & Beam	BSH/BTH
0.635 mm	Q Series [®] Strip	Blade & Beam	QSS/QTS
	Basic Strip	Blade & Beam	BSS/BTS
0.80 mm	Edge Rate [®] Strip	Edge Rate [®]	ERF8/ERM8
	Edge Card	Edge Rate [®]	HSEC8
	Q Rate [®] Strip	Edge Rate [®]	QRM8/QRF8
	Q Series [®] Strip	Blade & Beam	QSE/QTE
	Basic Strip	Blade & Beam	BSE/BTE
1.00 mm	Strip	Tiger Eye [™]	SEM/TEM
	SEARAY [™] Array	Edge Rate [®]	SEAF/SEAM
1.27 mm	Strip	Tiger Eye [™]	SFM/TFM
	Strip	Tiger Claw [™]	CLP/FTSH
	Strip	Tiger Beam [™]	FLE/FTSH
2.00 mm	Strip	Tiger Eye [™]	SMM/TMM
	Strip	Tiger Claw [™]	CLT/TMMH
2.54 mm	Strip	Tiger Claw [™]	SSM/TSM
	Strip	Tiger Claw [™]	BCS/TSW

* Tested socket/terminal combination shown. Other mating headers also available. Contact Samtec if header design you need is not shown.

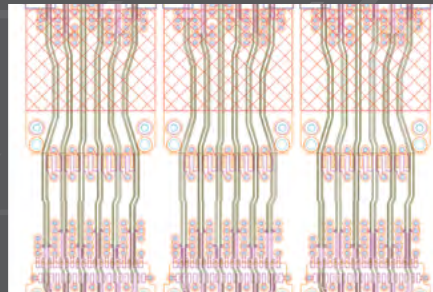
FULL SYSTEM SIGNAL INTEGRITY

Teraspeed® and Signal Integrity Group Engineers Help Optimize and Validate Your High-Performance System. Services are available at any level you require: from early stages of the design process including package design, materials selection and PCB routing, through in-depth analysis, modeling and simulation, with measurement validation services available to 67 GHz.



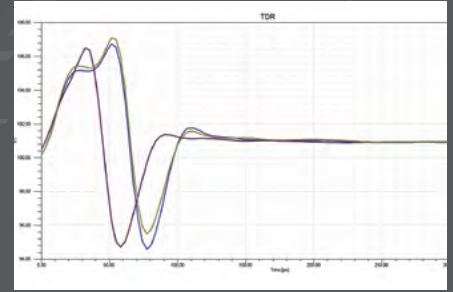
PACKAGE DESIGN & MATERIALS

- Bumpout / Ballout Optimization
- Layout & Routing
- Ballout Transition Structures
- Material Recommendations



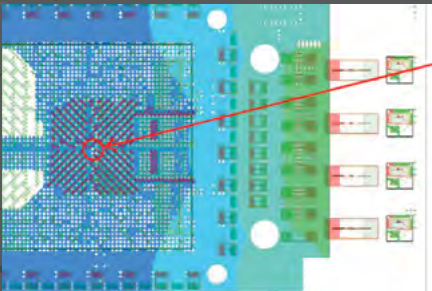
MODELING

- High Bandwidth Full-Wave
- Custom & Commercial Software



SIMULATION

- Design Rules for Package & PCB Designs
- Validate Implementation and Signaling Requirements for Critical Channels
- Simulations via High-Performance Computing



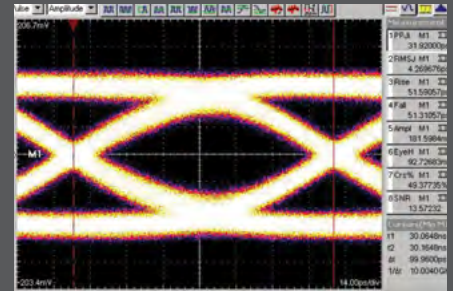
ANALYSIS

- Package, PCB and System-Level Power Integrity
- Package, PCB and System-Level Signal Integrity



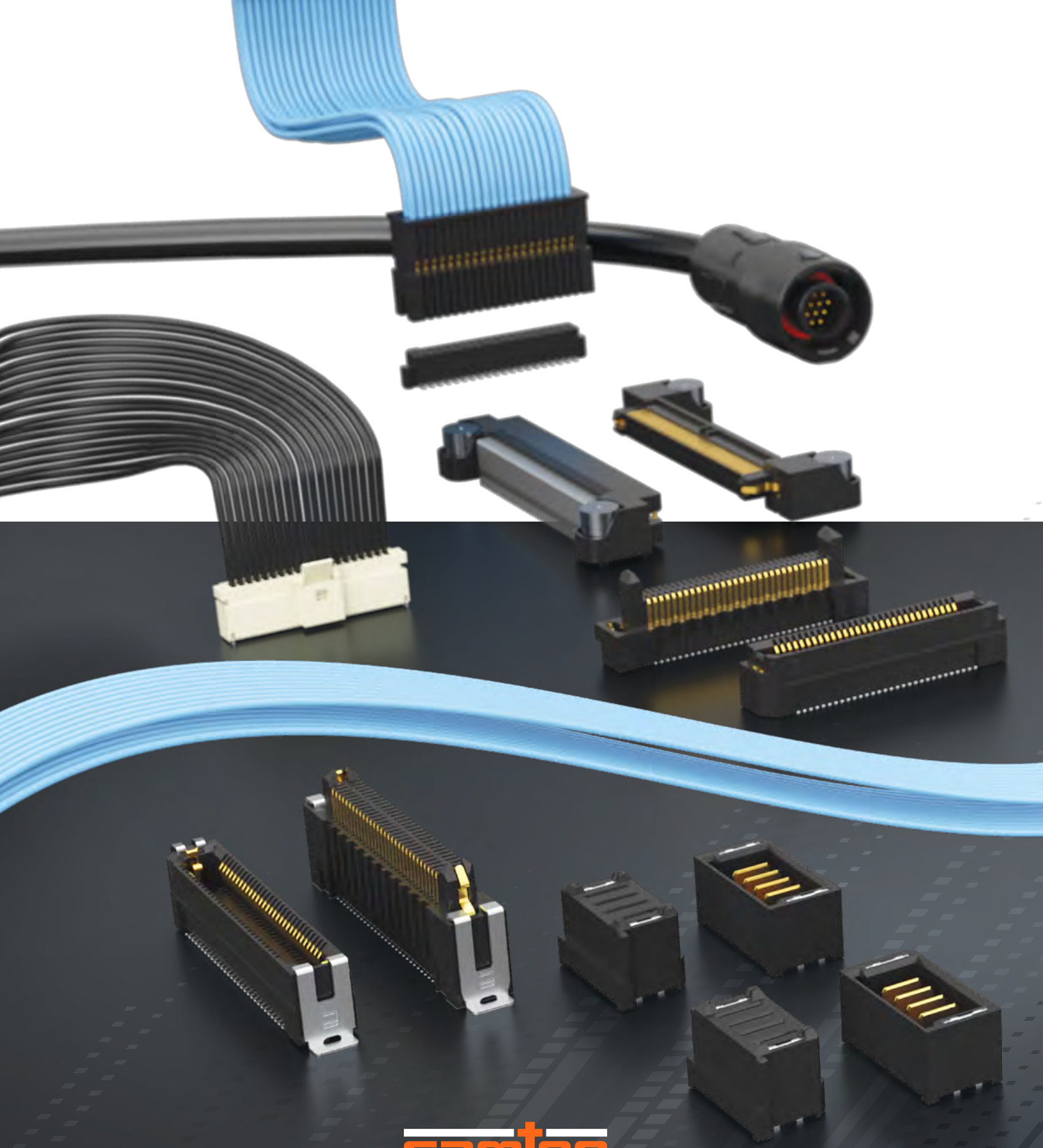
TESTING

- Post Design Simulation & Measurements
- Measurement of Test Structures for Signal Integrity / Power Integrity Optimization
- Material Characterization



VALIDATION

- Validation Platform Engineering
- Connectors, Packages & Devices
- Characterization at Frequencies to 67 GHz



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FEBRUARY 2017